

1 ABSTRACT

2 A face-to-face multi-chip flip-chip package comprises a first chip, at least a second
3 chip and a package substrate. The package substrate has a top surface, a bottom surface
4 and a concave wall between the top surface and the bottom surface. The second chip is
5 flip-chip mounted on active surface of the first chip. The first chip is mounted on the
6 package substrate so that the second chip is placed inside a chip accommodation space of
7 the package substrate which is defined by the concave wall. Side surfaces of the second
8 chip have a progressive distance from the chip accommodation space for lessening
9 capillary flow of underfilling material between the concave wall of the package substrate
10 and the side surfaces of the second chip during dispensing the underfilling material.